



LAND PATTERN RECOMMENDATIONS

- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 - B) ALL DIMENSIONS ARE IN MILLIMETERS
 - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 - D) PACKAGE SURFACE VOID SHALL NOT EXCEED 2.3 x 2.3 x 1.0mm
 - E) () IS REFERENCE
 - F) [] IS ASS'Y QUALITY
 - G) DRAWING FILENAME: MOD34BAREV2.0
 - H) FAIRCHILD SEMICONDUCTOR